



Final Product Change Notification

202607034F01 : PCA9532PW TSSOP24 Wire Conversion from Gold to Copper

Note: This notice is NXP Company Proprietary.

Issue Date: Aug 14, 2026 **Effective Date:** Dec 04, 2026

Dear Emma Tempest,

Here is your personalized communication about an NXP notification.
For detailed information we invite you to [view this notification online](#)

Management summary

NXP will change the wire for the bonding of the PCA9532PW products, from gold to copper for improved manufacturing logistics. This will align the manufacturing process and flow of this product to industry/factory standard.

Change Category

☐ Wafer Fab Process	☐ Assembly Process	☐ Product Marking	☐ Test Process	☐ Design
☐ Wafer Fab Materials	☒ Assembly Materials	☐ Mechanical Specification	☐ Test Equipment	☐ Errata
☐ Wafer Fab Location	☐ Assembly Location	☐ Packing/Shipping/Labeling	☐ Test Location	☐ Electrical spec./Test coverage
☐ Firmware	☐ Other			

Notification Overview

Description

ATBK will convert to Copper wire BOM (Bill of materials) for this product.

BOM information for TSSOP24 package:

- Wire type from Au/25um to Cu/20um
- Mold compound from GE-7470 to EMC, CEL8240
- Leadframe material from CuFe2P(NiPdAu) to CuFe2P(RT-NiPdAu)
- Die attach material QMI-519 (no change)

Reason

Copper wire will reduce logistics risks in production, by moving the product(s) to latest factory standards.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Jan 01, 2027

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing data sheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification:[view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Sep 13, 2026.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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